

Morgan J. Chen, Ph.D.

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US Citizen

OBJECTIVE

Lead multidisciplinary engineering teams with the purpose of developing and producing technology for the benefit human advancement in areas of RF/Microwave design, electromagnetic (EM) design, signal integrity, high-speed IC and module design, and advanced packaging integration

LANGUAGE

Native English, basic Mandarin Chinese, and basic Spanish

EDUCATION

Ph.D., Electrical and Computer Engineering

University of California, Davis, (UCD) California, March 2008

Thesis Topic: Development of Liquid Crystal Polymer (LCP) Multilayer Multi-Chip Modules for RF MEMS

Thesis Advisor: Professor Anh-Vu H. Pham

B.S., Electrical Engineering and Computer Science

University of California, Berkeley, (UCB) California, May 2003

EXPERIENCE

Manager, Electrical Engineering, Northrop Grumman, Woodland Hills, California, January 2024 to Present

- *Functional Manager* for team of 13 Principal Investigators, Subject Matter Experts, and support staff developing quantum sensor technologies for future Positioning, Navigation, and Timing (PNT)
- *Design support and test* of part obsolescence driven redesign in legacy Zero-Lock Laser Gyroscope (ZLG) product line

Director, Electrical Engineering, Lucix, Camarillo, California, August 2023 to December 2023

Director, Advanced Development, Lucix, Camarillo, California, May 2021 to August 2023

- *Manage Multiple Engineering Design Teams* covering Amplifier, Converter, Master Local Oscillator, & Passives product lines with annual revenues of \$40M. Introduced and established new concepts for integrated product teams in coordination with program office and operations. Track schedule and on-time delivery KPIs. On/off-boarded team members from requisition to hire. Adjust company culture to recognize individual and team success, encourage cross-training knowledge sharing, and establish standardized rigorous design reviews, processes, and checklists.
- *Develop new Amplifier product line in 2021.* Worked collaboratively with operations and quality departments to establish new travelers/processes, quality requirements and inspection criteria of high-power Gallium Nitride (GaN) devices, setup physical test environment including equipment procurement and fixturing, and setup new test procedures and practices required for Solid-State Power Amplifiers operating with >50W RF output power through Thermal Vacuum conditions (Multipaction/Corona).
- *Directly manage 9 direct reports* composed of a mix of in-office, hybrid, and full-remote work agreements. Multidisciplinary engineering staff have cradle-to-grave product support responsibilities including proposals, design, test, production support, and customer validation/support for RF products covering frequencies from 0.01 GHz to >30 GHz.

- *Generate* roadmaps with inputs from SMEs, business development team, and suppliers to address future market needs and present IRD proposals to Executive team. Generate technical packages for new proposals. Lead approved IRDs with cost/schedule planning, team assignment, and streamlined engineering gate processes through NASA Technology Readiness Level (TRL) 5. Provide senior technical inputs to resolve on issues that are beyond the experience of current design engineers. Review Subcontractor Data Requirements List (SDRLs). Promote a culture of continuous improvement and lead technical investigations during Failure Review Boards (FRBs) and Correction Action Requests (CARs). Represent Engineering during ISO9001 auditing.

Director, Advanced Technology and Product Development, L3Harris Technologies (L3 Technologies),
Folsom, California, March 2019 to May 2021

Manager, Advanced Technology and Product Development, L3Harris Technologies (L3 Technologies),
Folsom, California, June 2017 to March 2019

- *Manage direct reports* comprised of 3 engineers supporting amplifier design engineering group. Responsibilities include technical mentorship, process compliance training, staff review, KPI reporting, audit support, and staff sizing with experiences in direct hires and terminations (voluntary and involuntary)
- *Overhaul* company quality processes with full rewrite/re-organization of engineering quality processes. Improved process documents through engineering organization and improved process efficiency through techniques including swim-lane and process maps. Participated in ISO9001 audits.
- *Direct* technical plans for LCAMP (linearized channel amplifier) and SSPA (solid-state power amplifier) spaceborne module product lines for commercial/defense satellite markets from L-band through V-Band frequencies. Successfully realize reduction in Engineering Model (EM) build time from standard 9 months to 5 months with proper coordination and leverage of existing material stock. Cost Accounting Management under Earned Value Management Systems (EVMS) including developing time-phased budgets and tracking engineering CPI/SPI metrics on programs totaling ~\$10M annually
- *Innovate* through IR&D developments including proposals, program management, full P&L responsibility, and execution. Develop collaborative university research and generate technology roadmap with successful execution to plan (as adjusted by executive team against business needs). Published on one such endeavor in realizing a linearized 10W K-band SSPA with 30% PAE. Participate as engineering delegate on continuous improvement (CI) board and manage engineering efforts for approved CI projects. Lead technical investigations of Material Review Boards (MRBs) and Corrective Action and Preventative Actions (CAPAs) including conducting interviews, generating 5-whys, Ishikawa diagrams, pareto charts, trend analysis, and mind-maps.
- *Technical interface* between customers and internal team through product life cycle from RFI/RFQ/proposal stage, compliance matrix generation, cost/price generation and review, product development, Subcontractor Data Requirements List (SDRLs) spanning design analysis and test plans, customer review presentation, new-product introduction, manufacturing and test development oversight, product delivery, to product Authorization-to-Ship and program close-out

Lead Engineer, Nokia Networks, Sunnyvale, California, October 2015 to May 2017

Principal Engineer, Nokia Technologies, Sunnyvale, California, February 2015 to October 2015

- *Mentor* work of junior engineers by directing day-to-day technical tasks and schedule, and coordinate with system and IC design stakeholders to create proposals and perform feasibility studies for future technical/industry directions
- *Lead* electrical package design for RF products across 700 MHz to 86 GHz including laminate MCMs and demo-boards engaging in EM/circuit co-simulation across chip line-up of front-end modules (FEM), PA modules, baseband transceiver, and digital front-end for 5G MU-MIMO consumer networking products including handsets and consumer premises equipment (CPE) released under ReefShark chipset product line
- *Design, model extraction, and characterization* of integrated circuits including high-power switches, attenuators, filters, and diplexers in multiple foundry processes at nodes from 130 nm to 45 nm SOI CMOS and integrated passive devices (IPD)

Staff Engineer, Futurewei, Huawei Technologies, Santa Clara, California, November 2010 to February 2015

- *Design and characterize opto-electro (OE) modulators* in 130 nm SOI CMOS silicon photonics using transient and harmonic balance techniques with devices measured to offer >20 GHz bandwidth with optical loss and extinction ratio suitable for 25G serial applications. Designs also consider driver interface, packaging effects, power distribution networks, and ESD structures
- *Design and characterize devices and 3D packages* in technologies including silicon, GaAs, SiGe, and InP including (TW/Lumped)-Mach-Zehnder Modulator, driver, and TIA to ensure operation at 100 GBPS and up
- *Develop drivers and TIAs* in collaboration with internal and external partners from initial concept through qualification to production in aspects of electrical specification, IC design, RF signal integrity, and Power Distribution Network (PDN) power integrity design. For example, developed in partnership the Vitesse 7982-40 (4x10G driver) to meet business requirements including system specifications, cost, and schedule. Another example includes 4x25G TIA that offers lowest power consumption available compared to similar COTS ICs
- *Design of Receiver Modules* including low-cost 40G DQPSK, 100G client-side CFP, and 100G line-side Integrated Coherent Receiver (ICR) transponder links for Optical Transport Network (OTN) covering aspects of contract manufacturing, RF and optical connectors, ceramic gold-box, thin-film and flex package design, 10:4 gearbox, PD arrays, mux, demux, TIAs, and EML drivers to satisfy RF budget and IEEE 802.3 standards
- *Develop characterization techniques* to capture optical s-parameters, eye-diagrams, sensitivity, BER vs. OSNR, group delay, chromatic dispersion, etc. on 40G/100G muxes/demuxes, PDs, receivers, TIAs, EML drivers, wideband amplifiers, TDCMs, etc. in modulation formats for NRZ, DP-QPSK, and PAM4
- *Directly Manage* one contract technician from recruitment, interview, hire, and daily assignments

Sr. Design Engineer, Endwave Corporation, San Jose, California, January 2008 to November 2010

- *IC Design and layout* for mixers, VCOs, prescalers, and amplifiers in GaAs, InP III-V technologies
- *Lead design and development of novel chip packages* including extremely broadband RF/microwave Quad Flat No-lead (QFN) interconnects, packages, and multi-chip modules (MCM) from DC to 70 GHz with unique technologies including overmold leadframe, air-cavity leadframe, air-cavity laminates, thin-film, and LTCC (ceramic). Considerations include product cost analysis, signal integrity, power integrity, thermal analysis, mechanical analysis, cross-sectioning, develop assembly processes, documentation, and qualification testing
- *Design of SMT passive filters* operating past 40 GHz. Products include EWF2601AK, EWF2602AK, EWF3801AK, EWF3802AK, EWF4201AK, EWF4202AK, and EWF4203AK
- *Design test fixtures and characterization techniques* to capture s-parameters (gain and return losses), NF, PiPo, P1dB/IP3, phase noise, modulation sensitivity, pushing, etc. on custom MMICs including VGAs, VVAs, MPAs, PAs, LNAs, VCOs, prescalers (frequency dividers), mixers, up/down converters, etc.
- *Manage technicians and PCB designers* to ensure work is properly completed according to business priorities (directly manage several contract employees and indirectly manage multiple full-time staff). Liason with suppliers and contract manufacturers. Report directly to VP of Engineering

Graduate Student Researcher, Microwave and Microsystems Laboratory (MML), Department of Electrical and Computer Engineering, UCD, August 2003 to December 2007

- Developed thin-film LCP packages for RF MEMS switches that were further integrated into a system-in-package (SiP) hybrid 2-bit true-time delay phase shifter
- Designed and fabricated a 4-bit long time delay circuit on multilayer LCP using COTS MEMS devices
- Managed and trained undergraduate and graduate students and wrote proposals for external funding for research

Teaching Experience, Department of Electrical and Computer Engineering, UCD,

- Demonstrated antenna design and realization for EEC 133 (Electromagnetic Radiation and Antenna Analysis), November 2006 to December 2006
- Head Teaching Assistant. Assisted instruction of EEC 130A (Introductory Electromagnetics), held office hours, graded exams, and guest lectured for two - 90 minute classes, September 2003 to December 2003

Researcher, General Electric Global Research Center, Niskayuna, New York, June 2004 to August 2004 and June 2005 to August 2005

- EM simulations for design of RF MEMS package
- Process development of an LCP (near) hermetic package for RF MEMS switches
- Design of a true-time delay (TTD) system-in-package (SiP) phase shifter module

Research Assistant, National Science Foundation (NSF) Summer Undergraduate Research Experience (SURE), Clemson University, Clemson, South Carolina, June to August 2002

- Analytically designed, fabricated, and measured patch antennas on Duroid substrate with HP 8719
- Designed and demonstrated prototype of a multi-band/multi-mode direct conversion transmitter for wireless applications operating at 1.9 GHz and 5.8 GHz

Research Assistant, Berkeley Sensor & Actuator Center (BSAC), Department of Electrical Engineering and Computer Science, UCB, January 2002 to May 2002

- Designed an optical device to measure small angle light intensity under group led by Prof. Kris Pister
- Surveyed and ordered commercially available devices
- Constructed and demonstrated working prototype

Software Engineer, Boeing Autometric Inc., May to August 2001

- Programmed geosurveillance imaging software for fighter planes
- Built framework for decoding and viewing military satellite images

Research Assistant, Berkeley Short-Channel IGFET Model (BSIM) Group, Department of Electrical Engineering and Computer Science, UCB, January to May 2001

- Verified SPICE model test outputs against measured device data in group led by Prof. Chenming Hu
- Worked closely with post-doc to ensure accurate reporting

SKILLS AND TECHNIQUES

- **Engineering and Technology Management**

Certificates in personnel management, conflict mediator (Superior Court of Ventura County), technology management, program management, and finance accounting. Coached project engineering skills to staff in both informal and formal setting emphasizing both hard technology skills along with soft skills including collaboration, timeliness, continuous improvement, mentorship, and quality.

- **Operations and Quality**

Developed traveler/routers for new product introduction (NPI), experienced in both high-mix/low-volume manufacturing and high-volume production, rapid prototyping, Poka Yoke design, specific/tailored technician training, 5S (+1) Methodology, 8D Methodology, Toyota Kata, Six Sigma (Company adapted Yellow, Orange, Green, Purple Belts), Kaizen, DMAIC, Root Cause Analysis (RCA), FMEA, Pareto, Histogram-based parts binning, Ishikawa (Fishbone) diagrams, Five Whys

- **On-wafer characterization**

Characterization of passive, active, and optical devices to 67 GHz employing Agilent E8361A & E8364B PNA, HP 8510C VNA, signal generators, couplers, isolators, circulators, Bessel filters, noise figure meter, phase noise analyzer, Agilent lightwave component analyzer (LCA), Chromatic Dispersion measurement system, optical power meter, variable optical attenuator (VOA), electrical and optical spectrum analyzers (OSA), oscilloscopes (DCA), and BERTs (BPGs & EAs), Cascade & Gigatest Probe Stations, Cascade/GGB microwave and DC probe cards, lensed fiber and fiber holders

- **Microwave Circuit Design**

Design, simulation, layout, and characterize using ANSYS (e-Physics, HFSS, Q3D, Designer), AutoCAD, AWR Microwave Office, Cadence (Virtuoso, Allegro), CST, Keysight ADS (layout, transient, harmonic

balance, momentum), Klayout, Mathcad, Matlab, Mentor Graphics (Pyxis, Calibre), Python, Solidworks, and Sonnet

- **Optical Transport Network Design**

Design, simulation, layout, and characterize chips and components such as photodiodes, TIAs, drivers, modulators, fan-out substrates, TOSAs, and ROSAs for systems past 100G employing Agilent ADS and Lumerical (DEVICES, MODE, FDTD, Interconnect) design software

- **Fabrication**

- Micro/nano cleanroom diffusion, CVD, photolithography, metallization, annealing, RIE processes
- Former superuser on E-beam Evaporator at UCD - maintained tool and trained new users, 2005
- Machine shop milling/lathe competency

PATENTS

1. **Chen, Morgan**; Miao, Rongsheng; Zheng, Xueyan; Li, Bo; Shen, Xiao; Bai, Yu Sheng, 2014. Miniature High Density Opto-Electronic Package, US Patent 9974163, filed December 28, 2012, granted May 15, 2018.
2. **Chen, Morgan**; Gu, Yifan; Lee, Hungyi; Gu, Liang; Dang, Yen; Lei, Gong; Cao, Yuming; Shen, Xiao; Bai, Yu Sheng, 2016. Distributed Mach-Zehnder Modulator (MZM) Driver Delay Compensation, US Patent 9964832, filed May 28, 2016, granted May 8, 2018.
3. **Chen, Morgan**; Xu, Qianfan; Lee, Hungyi; Gu, Yifan; Gu, Liang; Dang, Yen; Lei, Gong; Cao, Yuming; Shen, Xiao; Bai, Yu Sheng, 2016. Digital Generation of Multi-Level Phase Shifting with a Mach-Zehnder Modulator (MZM), US Patent 9838239, filed January 7, 2016, granted December 5, 2017.
4. Zheng, Xueyan; Zheng, Dawei; Shen, Xiao; **Chen, Morgan**; Lei Hongbing, 2015. Digital Optical Modulator for Programmable n-Quadrature Amplitude Modulation Generation, US Patent 9531478, filed November 8, 2013, granted December 27, 2016.
5. Liao, Chunlei; **Chen, Morgan**; Shen, Xiao A.; Bai, Yusheng, 2014. Hybrid Integration Using Folded Mach-Zehnder Modulator Array Block, US Patent 9477134 B2, filed December 28, 2012, granted October 25, 2016.

BOOK PUBLICATIONS

1. A.-V. H. Pham, **M. J. Chen**, K. Aihara, *LCP for Microwave Packages and Modules: Design and Fabrication Techniques for Multi-layer Applications*, Cambridge University Press, 2012.
2. M. P. McGrath, K. Aihara, **M. J. Chen**, C. Chen, A.-V. Pham, "Liquid Crystal Polymer for RF and Millimeter-Wave Multi-Layer Hermetic Packages and Modules," in *RF and Microwave Microelectronics Packaging*, Springer New York, edited by K. Kuang, F. Kim, S. S. Cahill. 2010.

JOURNAL PUBLICATIONS

1. **M. Chen**, W. Kennan, "IMS2016 Special and Focus Sessions" IEEE Microwave Magazine, Vol. 17, No. 4, pp. 26-27, April 2016.
2. K. Aihara, **M. J. Chen**, A.-V. Pham, "Reliability of Liquid Crystal Polymer Air-Cavity Packaging" IEEE Transactions on Components, Packaging, and Manufacturing, Vol. 2, No. 2, pp. 224-230, February 2012.

3. **M. J. Chen**, Z. Zhang, A.-V. H. Pham, D. Hyman, "Design and Development of a Thin-Film Liquid Crystal Polymer Amplitude Compensated Long Time Delay Circuit," Wiley InterScience Microwave and Optical Technology Letters, Vol. 51, Np. 4, pp. 1060-1063, April 2009.
4. K. Aihara, **M. J. Chen**, A.-V. Pham, "Development of Thin-Film Liquid Crystal Polymer Surface Mount Packages for Ka-band Applications" IEEE Transactions on Microwave Theory and Techniques, Vol. 56, No. 9, pp. 2111-2117, September 2008.
5. **M. J. Chen**, A.-V. Pham, N. Evers, C. Kapusta, J. Iannotti, W. Kornrumpf, J. Maciel, "Multilayer Organic Multi-Chip Module Implementing Hybrid Microelectromechanical Systems," IEEE Transactions on Microwave Theory and Techniques, Vol. 56, No. 4, pp.952-958, April 2008.
6. A. C. Chen, **M. J. Chen**, A.-V. Pham, "Development of an RF Ultra-Wide Band Balun in Multi-layer Liquid Crystal Polymer Flex," IEEE Transactions on Advanced Packaging, Vol. 30, No. 3, pp. 533-540, August 2007.
7. **M. J. Chen**, A.-V. Pham, C. Kapusta, J. Iannotti, W. Kornrumpf, N. Evers, J. Maciel, "Design and Development of a Hermetic Package using LCP for RF/Microwave MEMS Switches," IEEE Transactions on Microwave Theory and Techniques, Vol. 54, No. 11, pp.4009-4015, November 2006.
8. **M. Chen**, "Single Chip Radio," California Engineer: Student Journal of the UC Engineering Colleges, Vol. 82, Issue 3, Spring/Summer 2004: pp. 4-8.

CONFERENCE PUBLICATIONS

1. **M. J. Chen**, L. Ralph, E. Rodgers, "Analog Predistortion of K-band GaN for 10W Linear Output Power and 30% Power Added Efficiency," IEEE WAMICON, April 28-29, 2021.
2. N. Robbins, D. Eze, H. Cohen, X. Zhai, W. McGeary, W. Menninger, **M. Chen**, E. Rodgers, "Space Qualified 200-W Q-band Linearized Traveling-Wave Tube Amplifier," International Vacuum Electronics Conference, Monterey, CA, April 23-26, 2018.
3. **M. J. Chen**, S. A. Tabatabaei, "Broadband, Quad Flat No-Lead (QFN) Package Developed using Standard Overmold Leadframe Technology," IEEE MTT-S Int. Microwave Symp. Dig., pp. 457-460, Anaheim, CA, May 23-28, 2010.
4. **M. J. Chen**, S. A. Tabatabaei, "Broadband, Thin-Film, Liquid Crystal Polymer Air-Cavity Quad Flat No-Lead (QFN) Package," IEEE Compound Semiconductor IC Symposium Digest, pp. 187-190, Greensboro, NC, October 11-14, 2009.
5. **M. J. Chen**, Z. Zhang, A.-V. H. Pham, D. J. Hyman, "Thin-Film LCP Amplitude Compensated Long Time Delay Circuit," IEEE MTT-S Int. Microwave Symp. Dig., pp. 141-144, Atlanta, GA, June 2008.
6. A.-V. Pham, K. Aihara, C. Chen, **M. Chen**, Z. Zhang, T. W. Dalrymple, "Performance of Surface Mount LCP Package Environmental Tests," GOMACTech, Las Vegas, NV, March 2008.
7. J. Iannotti, C. Kapusta, W. Taft, A. Jacomb-Hood, **M. Chen**, A.-V. Pham, "Wideband Passive Amplitude Compensated True Time Delay (TTD) Module for Active Phase Arrays," [GOMACTech](#), Lake Buena Vista, FL, March 19-22, 2007.
8. **M. Chen**, N. Evers, C. Kapusta, J. Iannotti, W. Kornrumpf, A.-V. Pham, J. Maciel, N. Karabudak, "Reliability of a Hermetic LCP Package for RF MEMS Switches," GOMACTech, Lake Buena Vista, FL, March 19-22, 2007.
9. N. Karabudak, J. Iannotti, N. Evers, **M. Chen**, A.-V. Pham, "Development of Hermetically Sealed for MEMS Modules Using Liquid Crystalline Polymer," 12th Ka and Broadband Communications Conference, Naples, Italy, September 27-29, 2006.

10. **M. Chen**, A. Pham, C. Kapusta, J. Iannotti, W. Kornrumpf, N. Evers, J. Maciel, N. Karabudak, "Development of Multilayer Organic Modules for Hermetic Packaging of RF MEMS Circuits," IEEE International Microwave Symposia, pp. 271-274, San Francisco, June 2006.
11. C. Tam, C. Chiang, M. Cao, **M. Chen**, M. C. Wong, J. K. Poon, K. Aihara, A. C. Chen, A. Vazquez, C. D. Johns, J. M. Frei, I. Kimukin, A. K. Dutta, M. S. Islam, "High speed pin photodetector with ultrawide spectral responses", Proc. SPIE Vol. 6014, Issue 1, pp. 291-296, Boston, MA, October 23, 2005.
12. **M. Chen**, N. Evers, C. Kapusta, J. Iannotti, A. Pham, W. Kornrumpf, J. Maciel, N. Karabudak, "Development of a Hermetically Sealed Enclosure for MEMS in Chip-on-Flex Modules using Liquid Crystal Polymer (LCP)", Proc. of the ASME Interpack '05, Part C, Page(s): 2057-2060, San Francisco, July 2005.
13. A.C. Chen, **M. Chen**, A. Pham, "Development of Microwave Ultra-Wide Band Balun using Liquid Crystal Polymer Flex", 55th IEEE Electronic Components and Technology Proceedings, 31 Page(s): 783 - 787, May 2005.

SELECTED PRESENTATIONS

1. Conference Speech, "Analog Predistortion of K-band GaN for 10W Linear Output Power and 30% Power Added Efficiency", IEEE WAMICON, Virtual, May 2021.
2. Workshop Speech, "Development of High-Speed Chip Package Interconnects," IEEE International Wireless Symposium (IWS), Xian, China, March 2014.
3. Workshop Speech, "Development of Quad Flat No-lead (QFN) Packages for Microwave Circuits," GOMACTech, Las Vegas, NV, March 2013.
4. Conference Speech, "Broadband, Quad Flat No-Lead (QFN) Package Developed using Standard Overmold Leadframe Technology", IEEE International Microwave Symposia, Anaheim, CA, May 2010.
5. Conference Speech, "Broadband, Thin-Film, Liquid Crystal Polymer Air-Cavity Quad Flat No-Lead (QFN) Package," IEEE Compound Semiconductor IC Symposium, October 2009.
6. Conference Speech, "Thin-Film LCP Amplitude Compensated Long Time Delay Circuit", IEEE International Microwave Symposia, Atlanta, GA, June 2008.
7. Conference Speech, "Liquid Crystal Polymer (LCP) for RF MEMS Packaging", 5th Annual MicroElectronics Packaging and Test Engineering Council (MEPTEC) MEMS Symposium, San Jose, CA, May 2007.
8. Conference Speech and Poster, "Development of Multilayer Organic Modules for Hermetic Packaging of RF MEMS Circuits," IEEE International Microwave Symposia, San Francisco, CA, June 2006.
9. Conference Speech, "Development of a Hermetically Sealed Enclosure for MEMS in Chip-on-Flex Modules using Liquid Crystal Polymer (LCP)", ASME InterPACK, San Francisco, July 2005.

PROFESSIONAL SERVICE

- Eta Kappa Nu, Electrical Engineering Honor Society
 - Life Member, 2000 to present
 - Mu Chapter Officer, EJC Representative, Fall 2001
- IEEE, Senior Member, August 1999 to present
 - Member of Microwave Theory and Techniques Society (MTT-S)
 - Editorial Review Board, Proceedings of the IEEE (PIEEE), 2016 to present
 - Editorial Review Board, Transactions on Microwave Theory and Techniques (TMTT), 2010 to present
 - Editorial Review Board, Microwave and Wireless Components Letters (MWCL), 2010 to present
 - International Microwave Symposium (IMS)
 - Judge, Industry/Advanced Practice Paper Competition, 2021-2022
 - Subcommittee Chair, Vice-Chair, and Member, Technical Paper Review Committee (TPRC)
 - Subcommittee on Packaging, Multi-chip Modules, and Manufacturing, 2010 to 2018
 - Subcommittee on Linearization and Transmitter Techniques for Power Amplifiers, 2019
 - Steering Committee, Focus and Special Session Chair, IMS 2016
 - Session Chair, various from 2012 to present
 - International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP)
 - TPC Member, IMWS-AMP 2022
 - International Wireless Symposium (IWS)
 - TPC Co-Chair, IWS 2016
 - TPC Co-Chair, IWS 2015
 - TPRC Co-Chair, IWS2015, SC13 and SC14
 - Workshop Chair, “High-Speed Link Design: From Devices to Systems” (full day), March 2014
 - Session Chair, IWS 2014
 - Workshop Chair, “THz Packaging Integration Technologies” (half day), April 2013
 - Workshop Chair, “THz Device Modeling” (half day), April 2013
- Asia Pacific Microwave Conference (APMC)
 - Member of Technical Paper Review Committee (TPRC) subcommittee A05, APMC 2014
 - Member of Technical Paper Review Committee (TPRC) subcommittee SC7, APMC 2009